Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An anisotropic conductive adhesive <u>material film</u>, for connecting a protuberant electrode of an electronic component to a terminal electrode of a circuit board for carrying the electronic component, the anisotropic conductive adhesive <u>material film</u> comprising at least one curable resin and silica particles, wherein:

the silica particles have a specific surface area $S(m^2/g)$ satisfying Equation (1) below;

$$11 < S \le 1711 \le S \le 17 \tag{1};$$

the silica particles have a mean particle size D_1 (μm) and maximum particle size D_2 (μm) satisfying Equations (2) and (3) below, respectively,

$$D_1 \le 5 \tag{2};$$

$$D_2 \le 0.5 (h_1 + h_2) \tag{3};$$

wherein h₁ represents the height of the protuberant electrode in the electronic component, and h₂ represents the height of the terminal electrode in the circuit board,

the content of the silica particles is 35 to 60 vol%, and

the mean particle size D_1 of the silica particles further satisfies the Equation (4) below,

$$0.1(h_1 + h_2) \ge D_1 \tag{4};$$

wherein the anisotropic conductive adhesive material-film further comprises conductive particles having a mean particle size of 0.5 to 8.0 μm ; and

wherein the anisotropic conductive adhesive material film has a coefficient of moisture absorption in a 85% RH, 85°C atmosphere is 1.5 wt % or less; and

wherein the anisotropic conductive adhesive film undergoes indentation of at least 10 μm at a 1 kgf indentation strength, and undergoes indentation of at least 15 μm at an indentation strength of 2 kgf, during thermocompression bonding for 20 seconds at 180°C.

- 2-5. (Canceled)
- 6. (Previously Presented) The adhesive material according to Claim 1, wherein the electronic component is a semiconductor element.
 - 7. (Canceled)